

METHOD AND SYSTEM TO MANUFACTURE STACKED CHIP DEVICES

ABSTRACT

A method and system for electrically interconnecting a semiconductor device and a component is presented. The semiconductor device includes a dielectric portion on at least one face thereof. Similarly, the component includes a dielectric portion on at least one face thereof. The device and component are constructed and arranged to be stacked and bonded together. A first laser selectively ablates the respective dielectric portions of the device and component. The ablating creates a starting pad on the device or component and a destination pad on the device or component. A second laser deposits a conductor along a path between the starting pad and destination pad. As such, smaller, more condensed electronic packages may be fabricated.